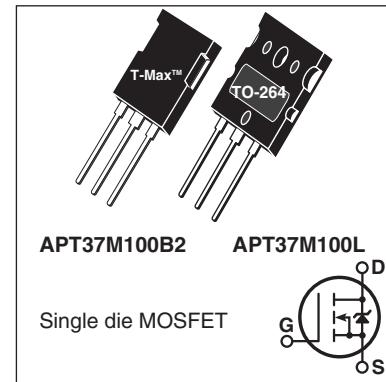


## N-Channel MOSFET

Power MOS 8™ is a high speed, high voltage N-channel switch-mode power MOSFET. A proprietary planar stripe design yields excellent reliability and manufacturability. Low switching loss is achieved with low input capacitance and ultra low  $C_{rss}$  "Miller" capacitance. The intrinsic gate resistance and capacitance of the poly-silicon gate structure help control slew rates during switching, resulting in low EMI and reliable paralleling, even when switching at very high frequency. Reliability in flyback, boost, forward, and other circuits is enhanced by the high avalanche energy capability.



### FEATURES

- Fast switching with low EMI/RFI
- Low  $R_{DS(on)}$
- Ultra low  $C_{rss}$  for improved noise immunity
- Low gate charge
- Avalanche energy rated
- RoHS compliant 

### TYPICAL APPLICATIONS

- PFC and other boost converter
- Buck converter
- Two switch forward (asymmetrical bridge)
- Single switch forward
- Flyback
- Inverters

### Absolute Maximum Ratings

Symbol	Parameter	Ratings	Unit
$I_D$	Continuous Drain Current @ $T_C = 25^\circ\text{C}$	37	A
	Continuous Drain Current @ $T_C = 100^\circ\text{C}$	23	
$I_{DM}$	Pulsed Drain Current <sup>①</sup>	140	
$V_{GS}$	Gate-Source Voltage	$\pm 30$	V
$E_{AS}$	Single Pulse Avalanche Energy <sup>②</sup>	2165	mJ
$I_{AR}$	Avalanche Current, Repetitive or Non-Repetitive	18	A

### Thermal and Mechanical Characteristics

Symbol	Characteristic	Min	Typ	Max	Unit
$P_D$	Total Power Dissipation @ $T_C = 25^\circ\text{C}$			1135	W
$R_{\theta JC}$	Junction to Case Thermal Resistance			0.11	$^\circ\text{C}/\text{W}$
$R_{\theta CS}$	Case to Sink Thermal Resistance, Flat, Greased Surface		0.11		
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55		150	$^\circ\text{C}$
$T_L$	Soldering Temperature for 10 Seconds (1.6mm from case)			300	
$W_T$	Package Weight		0.22		oz
			6.2		g
Torque	Mounting Torque (TO-264 Package), 4-40 or M3 screw			10	in-lbf
				1.1	N·m

## Static Characteristics

$T_J = 25^\circ\text{C}$  unless otherwise specified

APT37M100B2\_L

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
$V_{BR(DSS)}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu\text{A}$	1000			V
$\Delta V_{BR(DSS)}/\Delta T_J$	Breakdown Voltage Temperature Coefficient	Reference to $25^\circ\text{C}, I_D = 250\mu\text{A}$		1.15		$\text{V}/^\circ\text{C}$
$R_{DS(on)}$	Drain-Source On Resistance <sup>③</sup>	$V_{GS} = 10V, I_D = 18\text{A}$		0.29	0.33	$\Omega$
$V_{GS(th)}$	Gate-Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 2.5\text{mA}$	3	4	5	V
$\Delta V_{GS(th)}/\Delta T_J$	Threshold Voltage Temperature Coefficient			-10		$\text{mV}/^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 1000\text{V}$			100	$\mu\text{A}$
		$V_{GS} = 0V$			500	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS} = \pm 30\text{V}$			$\pm 100$	nA

## Dynamic Characteristics

$T_J = 25^\circ\text{C}$  unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
$g_{fs}$	Forward Transconductance	$V_{DS} = 50\text{V}, I_D = 18\text{A}$		39		S
$C_{iss}$	Input Capacitance	$V_{GS} = 0V, V_{DS} = 25\text{V}$ $f = 1\text{MHz}$		9835		pF
$C_{rss}$	Reverse Transfer Capacitance			130		
$C_{oss}$	Output Capacitance			825		
$C_{o(cr)}^{\text{④}}$	Effective Output Capacitance, Charge Related	$V_{GS} = 0V, V_{DS} = 0\text{V to } 667\text{V}$		335		pF
$C_{o(er)}^{\text{⑤}}$	Effective Output Capacitance, Energy Related			170		
$Q_g$	Total Gate Charge	$V_{GS} = 0$ to $10\text{V}$ , $I_D = 18\text{A}$ , $V_{DS} = 500\text{V}$		305		nC
$Q_{gs}$	Gate-Source Charge			55		
$Q_{gd}$	Gate-Drain Charge			145		
$t_{d(on)}$	Turn-On Delay Time	<b>Resistive Switching</b> $V_{DD} = 667\text{V}, I_D = 18\text{A}$ $R_G = 2.2\Omega^{\text{⑥}}$ , $V_{GG} = 15\text{V}$		44		ns
$t_r$	Current Rise Time			40		
$t_{d(off)}$	Turn-Off Delay Time			150		
$t_f$	Current Fall Time			38		

## Source-Drain Diode Characteristics

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
$I_s$	Continuous Source Current (Body Diode)	MOSFET symbol showing the integral reverse p-n junction diode (body diode)			37	A
$I_{SM}$	Pulsed Source Current (Body Diode) <sup>①</sup>				140	
$V_{SD}$	Diode Forward Voltage	$I_{SD} = 18\text{A}, T_J = 25^\circ\text{C}, V_{GS} = 0\text{V}$			1	V
$t_{rr}$	Reverse Recovery Time	$I_{SD} = 18\text{A}^{\text{③}}$ $dI_{SD}/dt = 100\text{A}/\mu\text{s}, T_J = 25^\circ\text{C}$		1165		ns
$Q_{rr}$	Reverse Recovery Charge			33		
$dv/dt$	Peak Recovery dv/dt	$I_{SD} \leq 18\text{A}, di/dt \leq 1000\text{A}/\mu\text{s}, V_{DD} = 100\text{V}, T_J = 125^\circ\text{C}$			10	V/ns

① Repetitive Rating: Pulse width and case temperature limited by maximum junction temperature.

② Starting at  $T_J = 25^\circ\text{C}$ ,  $L = 13.36\text{mH}$ ,  $R_G = 2.2\Omega$ ,  $I_{AS} = 18\text{A}$ .

③ Pulse test: Pulse Width < 380μs, duty cycle < 2%.

④  $C_{o(cr)}$  is defined as a fixed capacitance with the same stored charge as  $C_{oss}$  with  $V_{DS} = 67\%$  of  $V_{(BR)DSS}$ .

⑤  $C_{o(er)}$  is defined as a fixed capacitance with the same stored energy as  $C_{oss}$  with  $V_{DS} = 67\%$  of  $V_{(BR)DSS}$ . To calculate  $C_{o(er)}$  for any value of  $V_{DS}$  less than  $V_{(BR)DSS}$ , use this equation:  $C_{o(er)} = -2.85E-7/V_{DS}^{2.2} + 5.04E-8/V_{DS} + 9.75E-11$ .

⑥  $R_G$  is external gate resistance, not including internal gate resistance or gate driver impedance. (MIC4452)

Microsemi reserves the right to change, without notice, the specifications and information contained herein.

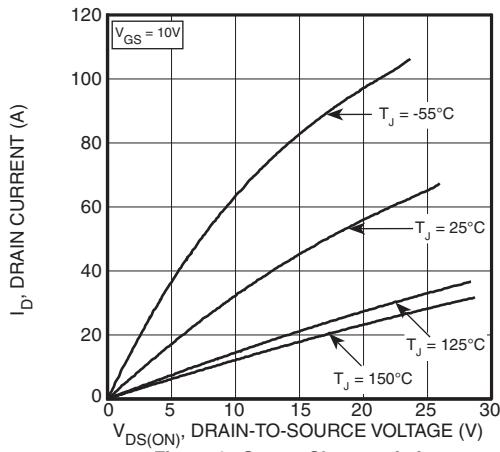


Figure 1, Output Characteristics

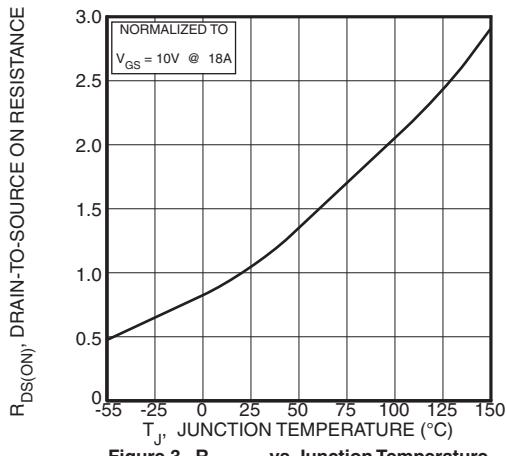
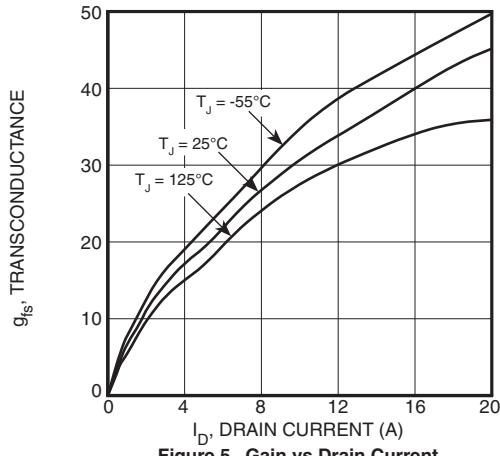
Figure 3,  $R_{DS(ON)}$  vs Junction Temperature

Figure 5, Gain vs Drain Current

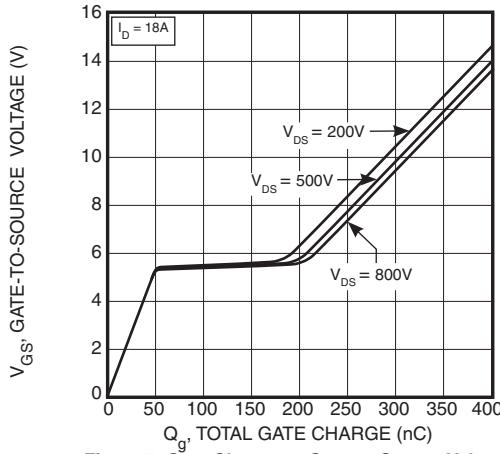


Figure 7, Gate Charge vs Gate-to-Source Voltage

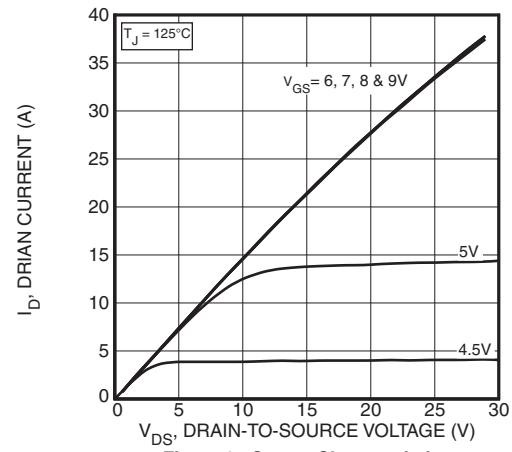


Figure 2, Output Characteristics

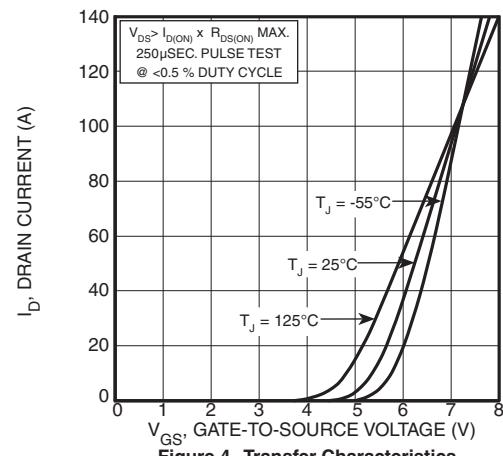


Figure 4, Transfer Characteristics

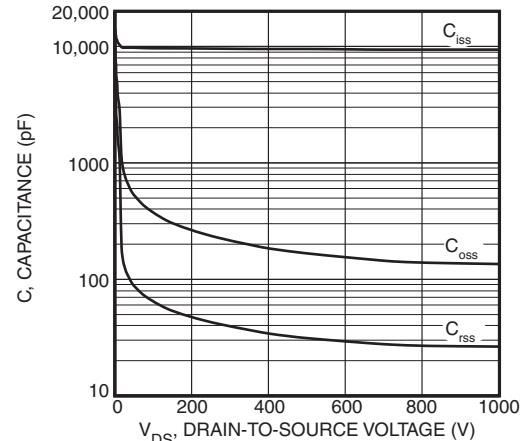


Figure 6, Capacitance vs Drain-to-Source Voltage

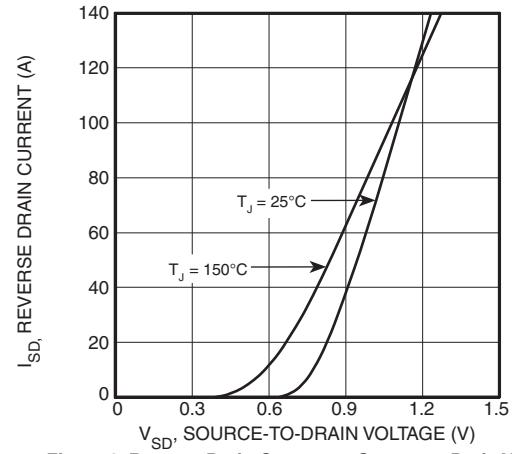


Figure 8, Reverse Drain Current vs Source-to-Drain Voltage

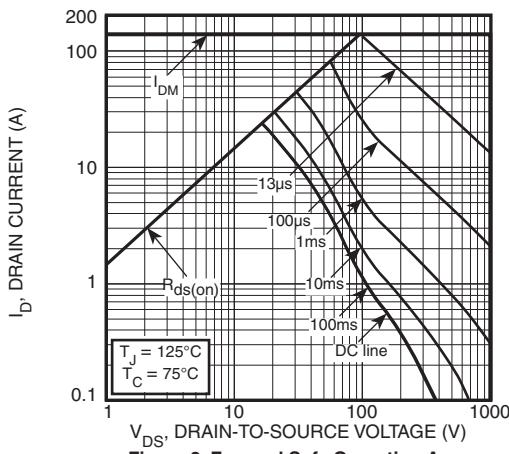


Figure 9, Forward Safe Operating Area

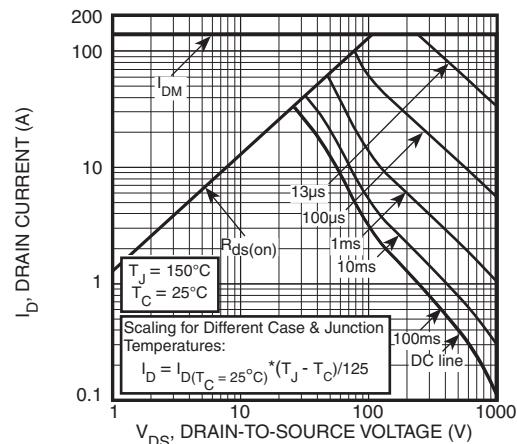


Figure 10, Maximum Forward Safe Operating Area

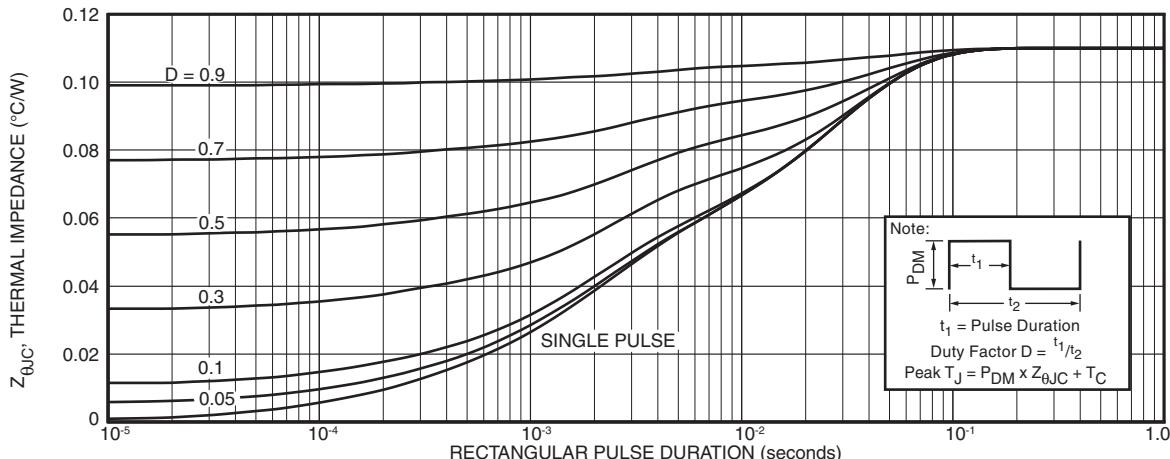
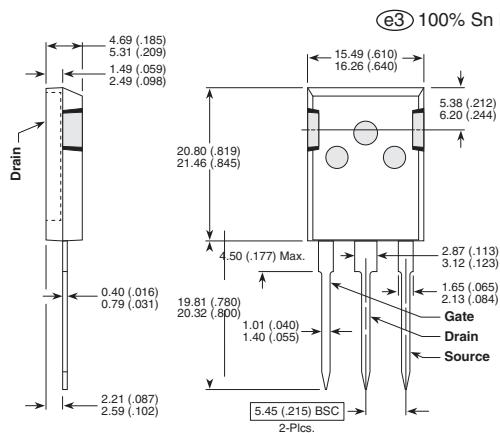
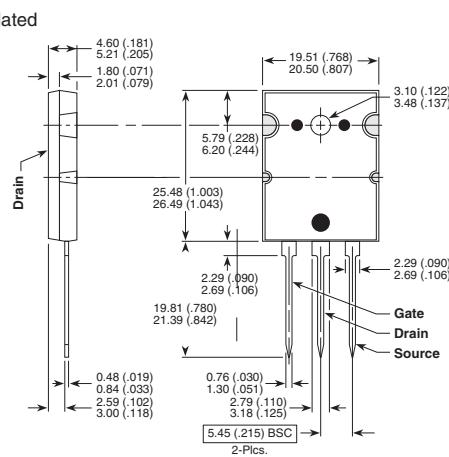


Figure 12. Maximum Effective Transient Thermal Impedance Junction-to-Case vs Pulse Duration

**T-MAX® (B2) Package Outline**

These dimensions are equal to the TO-247 without the mounting hole.

Dimensions in Millimeters and (Inches)

**TO-264 (L) Package Outline**

Dimensions in Millimeters and (Inches)

ООО "ЛайфЭлектроникс"

"LifeElectronics" LLC

ИНН 7805602321 КПП 780501001 Р/С 40702810122510004610 ФАКБ "АБСОЛЮТ БАНК" (ЗАО) в г.Санкт-Петербурге К/С 30101810900000000703 БИК 044030703

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибуторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибуторских договоров

Мы предлагаем:

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- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

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Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



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